BTA204X series D, E and F

GENERAL DESCRIPTION

Passivated guaranteed commutation triacs in a plastic full pack envelope, intended for use in motor control circuits or with other highly inductive loads. These devices balance the requirements of commutation performance and gate sensitivity. The "sensitive gate" E series and "logic level" D series are intended for interfacing with low power drivers, including micro controllers.

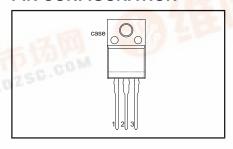
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
V _{DRM}	BTA204X- BTA204X- BTA204X- Repetitive peak	500D 500E 500F 500	600D 600E 600F 600	- 800E 800F 800	V
I _{T(RMS)}	off-state voltages RMS on-state current Non-repetitive peak on-state current	4 25	4 25	4 25	A A
			4	去饭	

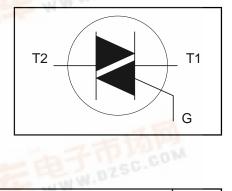
PINNING - SOT186A

PIN	DESCRIPTION			
1	main terminal 1			
2	main terminal 2			
3	gate			
case	isolated			

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.		MAX.		UNIT
V_{DRM}	Repetitive peak off-state voltages	THE COM	9	-500 500 ¹	-600 600 ¹	-800 800	V
I _{T(RMS)}	RMS on-state current	full sine wave;	-		4		A
I _{TSM}	Non-repetitive peak on-state current	$T_{hs} \le 92 ^{\circ}C$ full sine wave; $T_j = 25 ^{\circ}C$ prior to surge t = 20 ms	_		25		A
		t = 16.7 ms	-	_	27		Α
	l ² t for fusing	t = 10 ms	7.0	411	3.1		A ² s
dl _⊤ /dt	Repetitive rate of rise of on-state current after triggering	$I_{TM} = 6 \text{ A}; I_G = 0.2 \text{ A};$ $dI_G/dt = 0.2 \text{ A}/\mu\text{s}$	814	医一	100		A/μs
I _{GM}	Peak gate current	E TOP	<i>-</i>		2		Α
V _{GM}	Peak gate voltage	CC COM	-		2 5 5		V W
P _{GM} P _{G(AV)}	Peak gate power Average gate power	over any 20 ms			o 0.5		l w
• G(AV)	Average gate power	period			0.0		
T _{stg} T _j	Storage temperature Operating junction temperature		-40 -		150 125		ů C

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ISOLATION LIMITING VALUE & CHARACTERISTIC

T_{hs} = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{isol}	R.M.S. isolation voltage from all three terminals to external heatsink	f = 50-60 Hz; sinusoidal waveform; R.H. ≤ 65%; clean and dustfree	-		2500	V
C _{isol}	Capacitance from T2 to external heatsink	f = 1 MHz	-	10	-	pF

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-hs}	Thermal resistance junction to heatsink	full or half cycle with heatsink compound without heatsink compound			5.5 7.2	K/W K/W
R _{th j-a}	Thermal resistance junction to ambient	in free air	-	55	-	K/W

STATIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.			UNIT
		BTA204X-			D	Е	F	
I _{GT}	Gate trigger current ²	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$ T2+ G+ T2+ G-	-	-	5 5	10 10	25 25	mA mA
l _L	Latching current	T2- G- $V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	-	5	10	25	mA
	-	Ť2+ G+ T2+ G- T2- G-	-	- -	6 9 6	12 18 12	20 30 20	mA mA mA
I _H	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	-	06	12	20	mA
$egin{array}{c} V_{T} \ V_{GT} \end{array}$	On-state voltage Gate trigger voltage	$I_T = 5 \text{ A}$ $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$ $V_D = 400 \text{ V}; I_T = 0.1 \text{ A};$	- - 0.25	1.4 0.7 0.4		1.7 1.5 -		V V
I _D	Off-state leakage current	$ \begin{aligned} & T_j = 125 \text{ °C} \\ & V_D = V_{DRM(max)}; \\ & T_j = 125 \text{ °C} \end{aligned} $	-	0.1		0.5		mA

² Device does not trigger in the T2-, G+ quadrant.

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DYNAMIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS		MIN.		TYP.	MAX.	UNIT
		BTA204X-	D	E	F			
dV _D /dt	Critical rate of rise of off-state voltage	V _{DM} = 67% V _{DRM(max)} ; T _j = 125 °C; exponential waveform; gate open circuit	20	30	50	-	-	V/μs
dl _{com} /dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}; T_j = 125 ^{\circ}\text{C};$ $I_{T(RMS)} = 4 \text{ A};$ $dV_{com}/dt = 20 \text{V}/\mu\text{s}; \text{ gate}$ open circuit	1.0	2.0	2.5	-	-	A/ms
dl _{com} /dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}; T_j = 125 ^{\circ}\text{C};$ $I_{T(RMS)} = 4 \text{ A};$ $dV_{com}/dt = 0.1 \text{V}/\mu\text{s}; \text{ gate}$ open circuit	5.0	-	-	-	-	A/ms
t _{gt}	Gate controlled turn-on time	$I_{TM} = 12 \text{ A}; V_D = V_{DRM(max)};$ $I_G = 0.1 \text{ A}; dI_G/dt = 5 \text{ A}/\mu s$	-	-	-	2	-	μs

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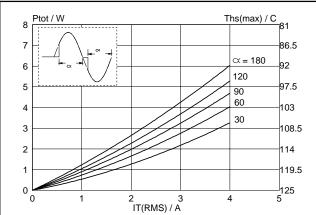


Fig.1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where α = conduction angle.

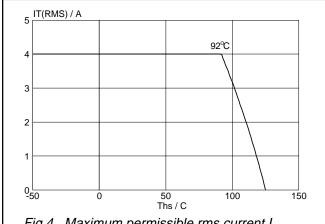


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus heatsink temperature T_{hs} .

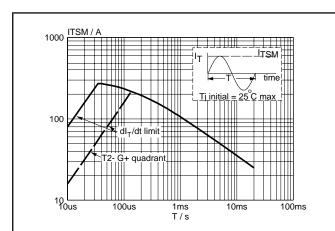


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \le 20$ ms.

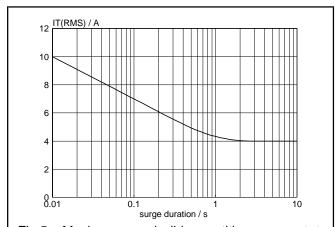


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{hs} \le 92$ °C.

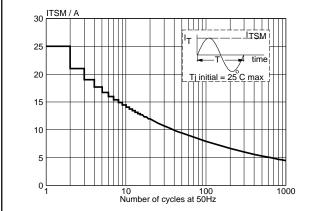


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, f = 50 Hz.

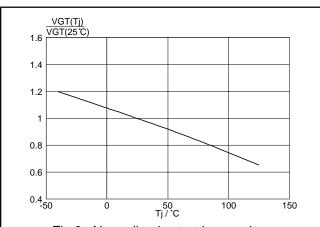
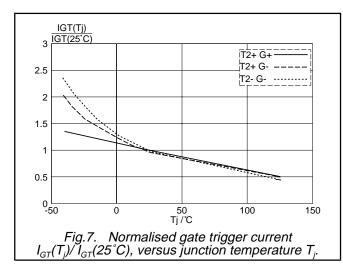
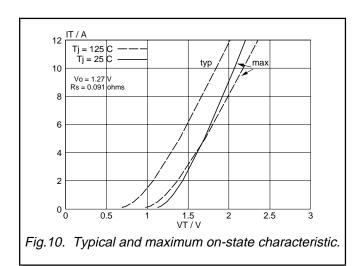
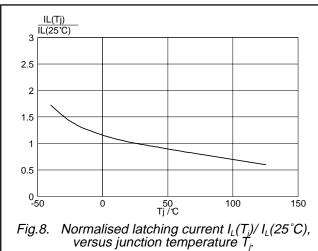


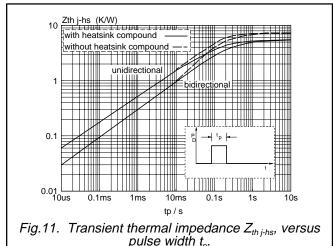
Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/V_{GT}(25^{\circ}C)$, versus junction temperature T_j .

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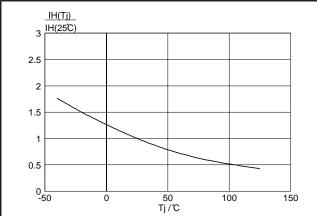
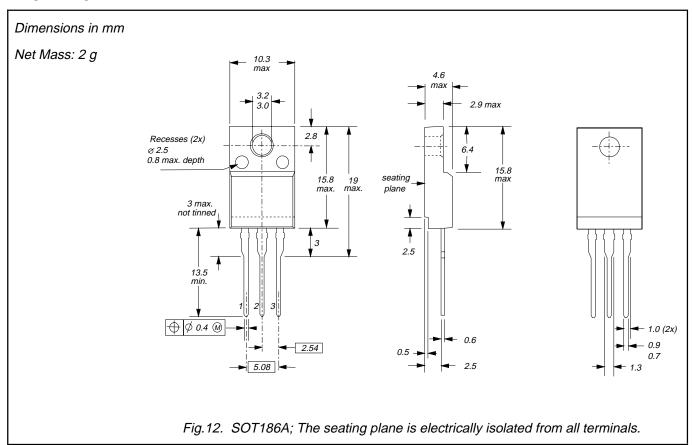


Fig.11. Transient thermal impedance $Z_{th\,j\text{-}hs}$, versus pulse width t_p .

Fig.9. Normalised holding current $I_H(T_i)/I_H(25^{\circ}C)$, versus junction temperature T_j .

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MECHANICAL DATA



- Refer to mounting instructions for F-pack envelopes.
 Epoxy meets UL94 V0 at 1/8".

BTA204X series D, E and F

DEFINITIONS

Data sheet status						
Objective specification	This data sheet contains target or goal specifications for product development.					
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.					
Product specification	This data sheet contains final product specifications.					
Limitin arrealises						

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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